

VLSI SOLUTION OY - VS1011E/LSR-ROHS - LQFP48 7 x 7 x 1.4 Document: A rev: 1.1

Component	Weight (mg)	Type	Material	CAS#	%	Weight (mg)	PPM of Total Weight
Chip	14.455		Silicon	7440-21-3	100.00	14.455	77975.751
Lead Frame	79.408	C7025	Copper	7440-50-8	96.20	74.834	403693.539
			Ni	7440-02-0	3.00	2.334	12589.196
			Si	7440-21-3	0.65	0.506	2727.659
			Mg	7439-95-4	0.15	0.117	629.460
		Ag	Silver	7440-22-4	100.00	1.618	8728.331
Mold Compound	86.394	SUMIKON EMEG700LX	Silica Fused	60676-86-0	87.50	75.595	407795.804
			Epoxy Resin	Trade Secret	4.00	3.456	18642.094
			Phenol Resin	Trade Secret	8.00	6.912	37284.188
			Carbon Black	1333-86-4	0.50	0.432	2330.262
Bonding Wire	0.640	Wire Dia : 1 mils	Au	7440-57-5	99.99	0.640	3452.142
			Dopant	-	0.01	0.000	0.345
Epoxy	1.577	CRM 1076DF	Silver (Ag)	7440-22-4	74.50	1.175	6337.823
			Epoxy Resin A	9003-36-5	11.50	0.181	978.322
			t-Butyl phenyl glycidyl ether	3101-60-8	7.50	0.118	638.036
			Butyl Cellosolve acetate	112-07-2	1.50	0.024	127.607
			Hardener	620-92-8	1.50	0.024	127.607
			1,1,1-Tris(p-hydroxyphenyl) ethane	27955-94-8	3.50	0.055	297.750
Plating	2.900	LEAD FREE Sn 100%	Sn	7440-31-5	99.987	2.900	15642.051
			Pb	7439-92-1	0.005	0.000	0.782
			Cu	7440-50-8	0.003	0.000	0.469
			Cd	7440-43-9	0.001	0.000	0.156
			Bi	7440-69-9	0.003	0.000	0.469
			Sb	7440-36-0	0.001	0.000	0.156
Total Weight	185.374					185.374	1000000.000